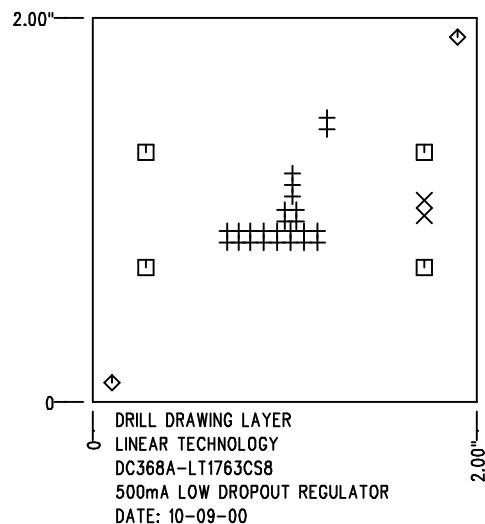


REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		

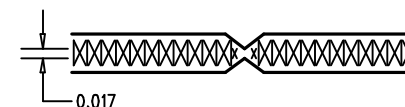


SHOWN FROM COMPONENT SIDE


SIZE	QTY	SYM	PLTD
0.02	25	+	PLTD
0.035	2	X	PLTD
0.064	4	□	PLTD
0.07	2	◇	NPLTD

#### NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE ELECTRODEPOSITED TIN-LEAD COMPOSITION BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 <b>LINEAR TECHNOLOGY</b>		1630 McCarthy Blvd Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE				
DRAWN			<b>TITLE: Fabrication Drawing</b> <b>500mA LOW DROPOUT REGULATOR</b>			
CHECK						
DESIGN	KIM T.	10-09-00				
ENGR	TODD O.	10-09-00				
			SIZE	DEMO	REV.	
			A	DC368A-LT1763CS8	A	
SCALE = NONE			DES- 0000		SHT 1 of 1	